IPC ASSOCIATION ELECTRONIC	© Copyrigh	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved un international and Pan-American copyright conventions.		nder both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lo level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
1752-21.1					Form Type * Distribute					rials and M	ials and Mfg Information				
Supplie	r Information														
Company name*			Company un	Company unique ID			Unique ID Authority				Respon	Response Date*			
nsemi											2024-04	2024-04-25			
Contact N	Name		Title - Conta	Title - Contact			Phone - Contact*				Email -	Email - Contact*			
Product-l	Env-Stewards		Product Envi	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
uthorize	ed Representative*		Title - Repres	Title - Representative			Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards			Product Envi	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item		tem Number	n Number Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
		NCP3	NCP303160MNTWG Integrated Driver & N		& MOSFFET		2024-04-25		MY5			86.36325	mg	Each	
Ianufa	ncturing Proccess In	nformation													
	8		Terminal Base	Terminal Base Alloy J-STD-		Rating			emperature	ure Max Time at Peak Temperature		ture Numbe	r of Reflow Cyc	eles	
Matte Tin (Sn) - annealed			CU Alloy	1			260		С	30	secor	nds 3			
omments															
<u>vel 1 - m</u>	naximum time at peak to	emperature during	soldering is 10-3	0 seconds											
or more	information regarding	material compositi	on please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-6_								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	6.80036	mg	Supplier	Zinc (Zn)	7440-66-6		0.0082	mg
			Supplier	Iron (Fe)	7439-89-6		0.1632	mg
			Supplier	Copper (Cu)	7440-50-8		6.6236	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0054	mg
Clip Attach	0.1	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0075	mg
			Supplier	Proprietary	Proprietary Data		0.0065	mg
			Supplier	Bismaleimide	13676-54-5		0.028	mg
			Supplier	PTFE	9002-84-0		0.058	mg
Die	2.76287	mg	Supplier	Silicon (Si)	7440-21-3		2.7629	mg
Die Attach Solder	4.40103	mg	Supplier	Silver (Ag)	7440-22-4		0.11	mg
			A	Lead (Pb)	7439-92-1	7a	4.071	mg
			Supplier	Tin (Sn)	7440-31-5		0.2201	mg
Lead Frame	32.9996	mg	Supplier	Silver (Ag)	7440-22-4		1.65	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0396	mg
			Supplier	Iron (Fe)	7439-89-6		0.792	mg
			Supplier	Copper (Cu)	7440-50-8		30.4916	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0264	mg
Mold Compound-Black	36.0995	mg		Proprietary	proprietary data		2.888	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1805	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		33.031	mg
Plating	2.99983	mg	Supplier	Tin (Sn)	7440-31-5		2.9998	mg
Wire Bond - Cu	0.200061	mg	Supplier	Palladium (Pd)	7440-05-3		0.0036	mg
			Supplier	Gold (Au)	7440-57-5		0.0002	mg
			Supplier	Copper (Cu)	7440-50-8		0.1963	mg